

Title (en)
REWORKABLE THERMOSETTING RESIN COMPOSITIONS

Title (de)
WIEDERVERARBEITBARE WÄRMEHÄRTBARE HARZZUSAMMENSETZUNGEN

Title (fr)
COMPOSITIONS DE RESINE THERMODURCISSABLES REMANIABLES

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Application
EP 00916567 A 20000322

Priority

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Abstract (en)
[origin: WO0056799A1] This invention relates to thermosetting resin compositions useful for mounting onto a circuit board semiconductor devices, such as chip size or chip scale packages ("CSPs"), ball grid arrays ("BGAs"), and the like, each of which having a semiconductor chip, such as large scale integration ("LSI"), on a carrier substrate. The compositions of this invention are reworkable when subjected to appropriate conditions.

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